

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
KEISUKE SUGITA	08/03/2016
AKINARI NAKAYAMA	08/03/2016
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<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15282182
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	YUWA.007
<b>NAME OF SUBMITTER:</b>	SEAN M. MCGINN
<b>SIGNATURE:</b>	/Sean M. McGinn/
<b>DATE SIGNED:</b>	10/04/2016
<b>Total Attachments: 2</b>	
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source=Assignment#page2.tif	

## Combined Declaration of Inventorship and Assignment of Application for Patent

As a below-named inventor, I hereby declare that:

I believe that I am the original inventor or an original joint inventor, of the claimed invention in the Application entitled:

### CONDUCTIVE ELASTOMER COMPOSITION AND MOLDED ARTICLE OF THE SAME

the specification of which (check one):

☒ is attached hereto

☐ was filed as U. S. Application No. or PCT International Application No. \_\_\_\_\_ on \_\_\_\_\_.

The Application was made or was authorized to be made by me. I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both. I have reviewed and understand the contents of the Application, including the claims, and I am aware of the duty to disclose to the U. S. P. T. O. all information known to be material to patentability as defined in 37 CFR §1.56.

The below-named inventor (hereinafter referred to as ASSIGNOR) having invented and owning a certain and new and useful invention which is the subject of the Application, and

Hitachi Metals, Ltd. (Full Name of Assignee)

2-70, Konan 1-chome, Minato-ku, Tokyo Japan (Address of Assignee)

(hereinafter referred to as ASSIGNEE), being desirous of acquiring the entire right, title, and interest in, to and under the invention which is the subject of the Application and the United States Letters Patent to be obtained therefor.

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that in consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNOR, by these presents, hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to said invention and all Letters Patent of the United States to be obtained therefor on said Application or any continuation, division, renewal, substitute or reissue thereof for the full term or terms for which the same may be granted.

ASSIGNOR hereby authorizes and requests Sean M. McGinn of McGinn Intellectual Property Law Group, PLLC, 8321 Old Courthouse Road, Suite 200, Vienna, Virginia, U.S.A. 22182-3817 to insert here in parentheses (Application No. 15/282,182 filed September 30, 2016) the filing date and Application number of said Application when/if known.

ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patent of the United States Patent obtained therefor on said Application or any continuation, division, renewal, substitute or reissue thereof for the full term or terms to said ASSIGNEE, of the entire right, title, and interest in and to the same, for his sole use and behoof, and for the use and behoof of his legal representatives, to the full end of the term or terms for which said Letters Patent obtained therefor on said Application or any continuation, division, renewal, substitute or reissue thereof for may be granted, as full and entirely as the same would have been held by ASSIGNOR had this Assignment and sale not been made.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain and enforce said application, said invention and said Letters Patent which may be necessary or desirable to carry out the purposes hereof.

Legal Name of Inventor Keisuke Sugita

Inventor's Signature Keisuke Sugita Date AUG. 3. 2016

Legal Name of Additional Inventor, If Any Akinari Nakayama

Inventor's Signature Akinari Nakayama Date AUG. 3. 2016

Legal Name of Additional Inventor, If Any \_\_\_\_\_

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

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Legal Name of Additional Inventor, If Any \_\_\_\_\_

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_